

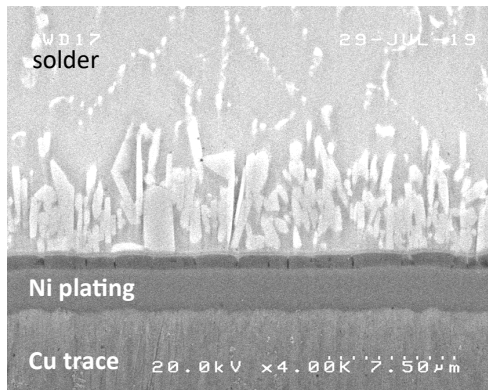
We help designers and manufacturers

- Reduce design cycle time
- Minimize customer product returns
- Maximize product yields

Failure Analysis Materials Analysis Reliability Testing Teardown Analysis

As the autumn is upon us, we are back to full capacity, ready to rise to new challenges. We are lucky to be a small team located in a large facility. This makes distancing relatively easy. We have added some infra-structure to be able to operate safely through a second wave.

The pandemic is disrupting supply chains. We are seeing an increase in black pad and its accompanying feather-like abnormal intermetallic formation.



SEM image of a solder joint cross-section showing severe nickel corrosion and feathered intermetallic region.

Contact us for IPC-A-600, IPC-A-610 and Dye and Pry evaluations of your printed circuits. You may be shocked by what we find.

Courses

We do have two half-day training courses available. We will deliver them remotely. Please contact us to get the outlines and to make arrangements if you are interested.

Failure Analysis of Electronic Devices

This half-day course will benefit design engineers, component engineers, and quality engineers who may not be familiar with the physics behind FA tools available to them, internally or externally, to resolve their customer returns or supplier quality issues.

Shining a light on LED technology: construction, reliability, qualification, failure modes

This half-day course will benefit design engineers, component engineers, quality engineers and patent lawyers who may not be familiar with the physics, internal structure and reliability issues of LEDs as components.

Read our paper on teardown of face mask materials in [EETimes](#)